



# DNP1101W

Surface Mount IRED/Flat Lenz Type

#### Features

Package	3216 type, Water clear epoxy	
Product features	<ul> <li>Outer Dimension 3.0 x 1.5 x 1.5mm (L x W x H)</li> <li>Flat Lenz Type</li> <li>Total Output Power : 5mW TYP. (I<sub>F</sub>=20mA)</li> <li>Lead-free soldering compatible</li> <li>RoHS compliant</li> </ul>	
Peak Wavelength	880nm	
Half Intensity Angle	$\theta x = 130 \text{ deg.},  \theta y = 135 \text{ deg.}$	
Die materials	GaAlAs	
Rank grouping parameter	Sorted by radiant intensity per rank taping	
Assembly method	Auto pick & place machine (Auto Mounter)	
Soldering methods	Reflow soldering and manual soldering XPlease refer to Soldering Conditions about soldering.	
Taping and reel	2,500pcs per reel in a 8mm width tape. (Standard) Reel diameter:¢180mm	
ESD	2kV (HBM)	

# **Recommended Applications**

Car Audio, Electric Household Appliances, OA/FA, PC/Peripheral Equipment, Other General Applications

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2004.11.17

STANLEY ELECTRIC CO., LTD.

# Absolute Maximum Ratings

Item	Symbol	Absolute Maximum Ratings	Unit
Power Dissipation	Pd	80	mW
Forward Current	I <sub>F</sub>	50	mA
Pulse Forward Current <sup>*1</sup>	I <sub>FRM</sub>	300	mA
Derating (Ta=25℃ or higher)	⊿I <sub>F</sub>	0.67	mA/°C
	⊿ I <sub>FRM</sub>	4	mA/°C
Reverse Voltage	V <sub>R</sub>	5	ν
Operating Temperature	T <sub>opr</sub>	-30~+85	C
Storage Temperature	T <sub>stg</sub>	-40~+100	C

**※1** IFRM Measurement condition : Pulse Width ≤  $100 \mu$  s, Duty ≤ 1/100

# **Electro-Optical Characteristics**

ltem		Symbol		Characteristics		
nem	Conditions	Symbol	on Characteristics		Unit	
Formward Vialtage	L _20m A	V <sub>F</sub>	TYP.	1.35	V	
Forward Voltage	I <sub>F</sub> =20mA		MAX.	1.6	v	
<b>Reverse Current</b>	V <sub>R</sub> =5V	I <sub>R</sub>	MAX.	100	μA	
			MIN.	0.5		
Radiant Intensity	I <sub>F</sub> =20mA	I <sub>F</sub> =20mA I <sub>E</sub>		1	mW/sr	
Total Output Power	I <sub>F</sub> =20mA	Ро	TYP.	5	mW	
Peak Wavelength	I <sub>F</sub> =20mA	λ <sub>p</sub>	TYP.	880	nm	
Spectral Half-width	I <sub>F</sub> =20mA	⊿λ	TYP.	40	nm	
		2 <del>0</del> 1/2	TYP.	130(θ x)	deg.	
Half Intensity Angle	I <sub>F</sub> =20mA			135(θy)		
	$I_F = 20 \text{mA}_{DC} \pm 5 \text{mA},$	fc	MIN.	-	MHz	
Cut-off Frequency	-3db from 0.1MHz		TYP.	12		
<b>Response Time</b>	I <sub>F</sub> =20mA	tr/tf	TYP.	30	ns	

# (Ta=25℃)

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Pb-free HEAT

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	NL

(Ta=25°C)

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# Radiant Intensity Rank

Rank	l <sub>E</sub> (m)	Condition	
Kallk	MIN.	MAX.	Continuon
Α	0.5	1.0	
В	0.7	1.4	
С	1.0	2.0	$I_F = 20 m A$
D	1.4	2.8	
E	2.0	4.0	

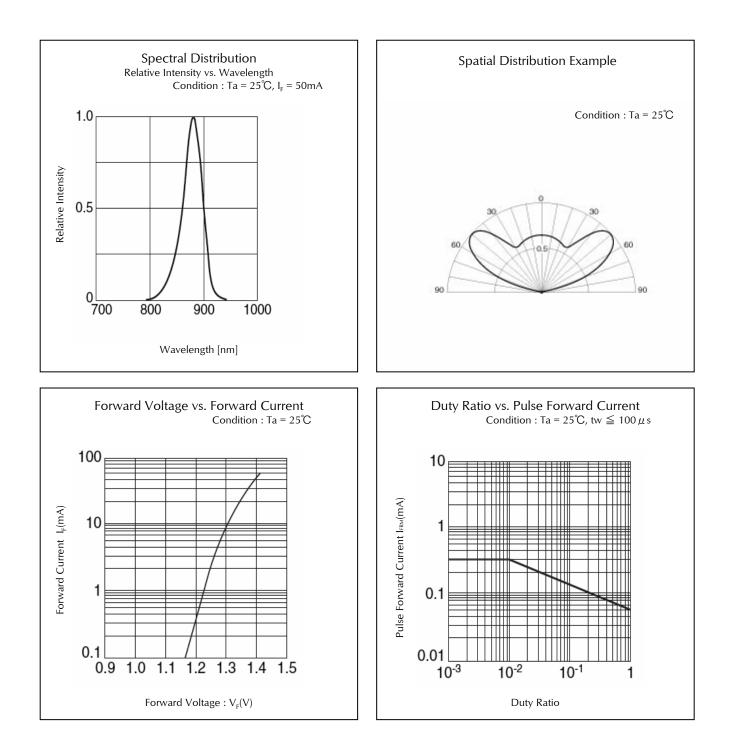
%Please contact our sales staff concerning rank designation.

#### (Ta=25℃)





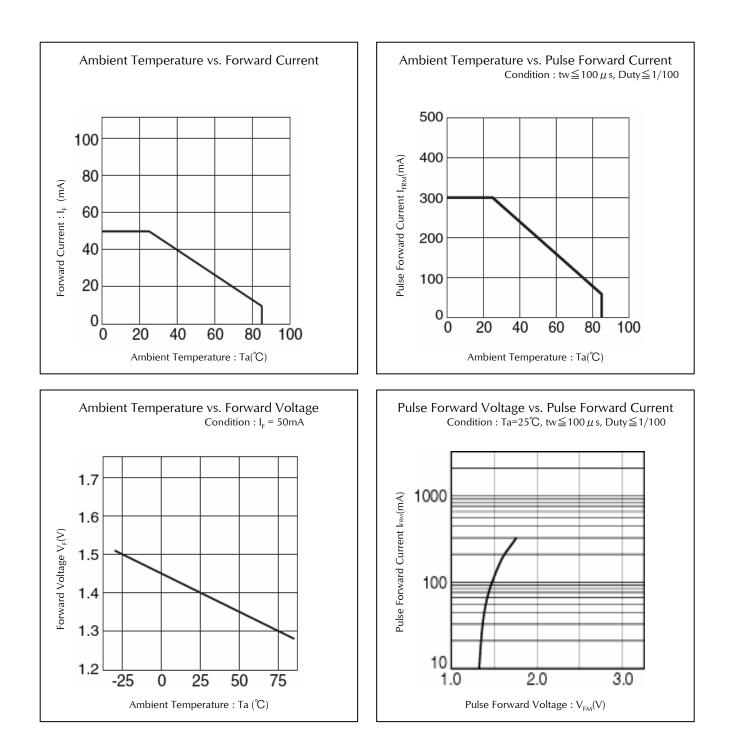
#### **Technical Data**







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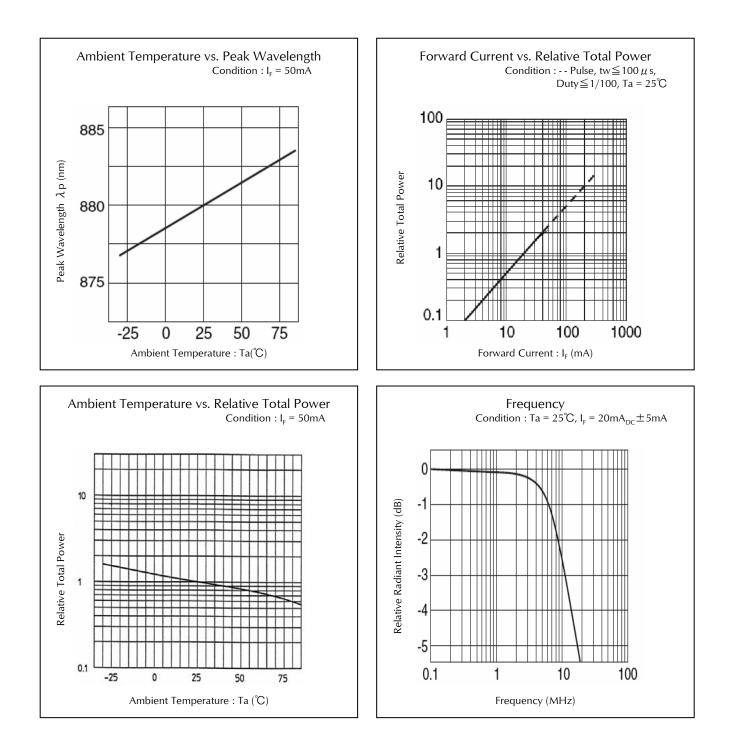




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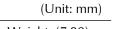
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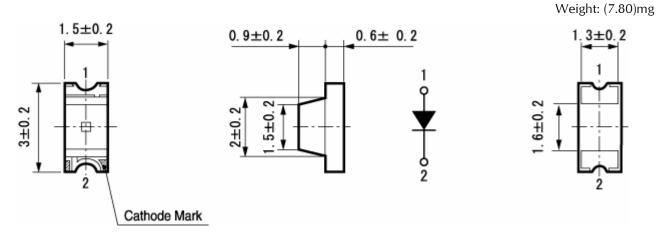




Pb-free HEAT DNP1101W Surface Mount IRED/Flat Lenz Type

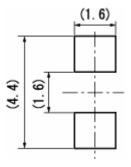
### Package Dimensions





### **Recommended Soldering Pattern**

(Unit: mm)

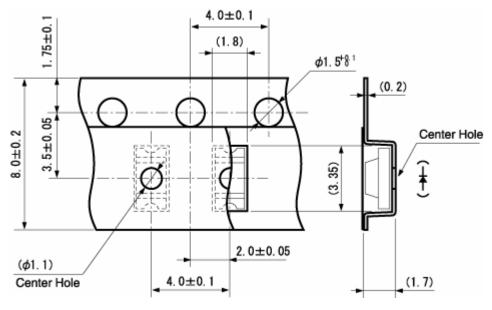


# **Taping Specification**

(Unit: mm)

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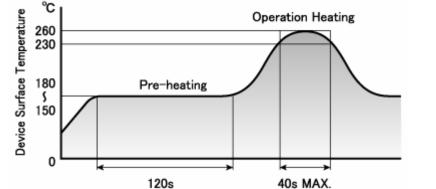








#### **Reflow Soldering Conditions**



- 1) The above profile temperature gives the maximum temperature of the LED resin surface. Please set the temperature so as to avoid exceeding this range.
- 2) Total times of reflow soldering process shall be no more than 2 times. When the second reflow soldering process is performed, intervals between the first and second reflow should be short as possible (while allowing some time for the component to return to normal temperature after the first reflow) in order to prevent the LED from absorbing moisture.
- 3) Temperature fluctuation to the LED during the pre-heating process shall be minimized.

#### Manual Soldering Conditions

Iron tip temp.	350 ℃	(MAX.) (30 W Max.)
Soldering time and frequency	3 s 1 time	(MAX.) (MAX.)



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# **Reliability Testing Result**

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED- 4701/100(101)	Ta = $25^{\circ}$ C, IF = Maxium Rated Current	1 <i>,</i> 000 h	0/25
Resistance to Soldering Heat	EIAJ ED- 4701/300(301)	(Pretreatment) Individual standard (Reflow Soldering) Pre-heating 150°C∼180°C 120s Operating Heating 230°C Min. Peak temperature 260°C	Twice	0/25
Temperature Cycling	EIAJ ED- 4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	5 cycles	0/25
Wet High Temp. Storage Life	EIAJ ED- 4701/100(103)	$Ta = 60 \pm 2^{\circ}C$ , RH = 90 $\pm 5\%$	1 <i>,</i> 000 h	0/25
High Temp. Storage Life	EIAJ ED- 4701/200(201)	Ta = Maximum Rated Storage Temperature	1 <i>,</i> 000 h	0/25
Low Temp. Storage Life	EIAJ ED- 4701/200(202)	Ta = Minimum Rated Storage Temperature	1 <i>,</i> 000 h	0/25
Vibration, Variable Frequency	EIAJ ED- 4701/400(403)	98.1m/s <sup>2</sup> (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

# Failure Criteria

ltems	Symbols	Conditions	Failure criteria
Radiant Intensity	Ι <sub>Ε</sub>	IF Value of each product Radiant Intensity	Testing Min. Value < Initial Value x 0.5
Forward Voltage	VF	I⊧ Value of each product Forward Voltage	Testing Max. Value > Spec. Max. Value x 1.2
Reverse Current	<b> </b> R	Vr = Maximum Rated Reverse Voltage V	Testing Max. Value $\geq$ Spec. Max. Value x 2.5



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